

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	717	257/707.ccls.	USPAT; US-PGPU
2	BRS	L2	758	257/783.ccls.	USPAT; US-PGPU
3	BRS	L3	217	257/789.ccls.	USPAT; US-PGPU
4	BRS	L4	1	4818812.pn.	USPAT; US-PGPU
5	BRS	L5	1	4388132.pn.	USPAT; US-PGPU
6	BRS	L6	1	6311888.pn.	USPAT; US-PGPU
7	BRS	L7	2	"10135386"	JPO
8	BRS	L8	2	"2002141439"	JPO
9	BRS	L9	0	"141439"	JPO
10	BRS	L10	2	"2002141439"	JPO
11	BRS	L12	22	L2 and resin and filler and particle and size and modulus	USPAT; US-PGPU B
12	BRS	L13	18	L3 and resin and filler and particle and size and modulus	USPAT; US-PGPU B
13	BRS	L14	66	(radiation adj plate) and (resin or adhesive) and filler	USPAT; US-PGPU B
14	BRS	L11	51	L1 and resin and thick and (heat or radiation) and plate	USPAT; US-PGPU B
15	BRS	L15	1	L11 and (chip near2 thickness)	USPAT; US-PGPU
16	BRS	L16	3	L13 and (chip near2 thickness)	USPAT; US-PGPU
17	BRS	L17	2	L12 and (chip near2 thickness)	USPAT; US-PGPU
18	BRS	L18	1	5308980.pn.	USPAT; US-PGPU
19	BRS	L19	101	L3 and resin and filler	USPAT; US-PGPU
20	BRS	L20	2	L19 and (first adj filler)	USPAT; US-PGPU
21	BRS	L21	60	257/707.ccls.	EPO; JPO; IBM_TDB
22	BRS	L22	1790	257/787.ccls.	EPO; JPO; IBM_TDB
23	BRS	L23	158	257/783.ccls.	EPO; JPO; IBM_TDB

	Type	L #	Hits	Search Text	DBs
24	BRS	L24	181	257/789.ccls.	EPO; JPO; IBM_TDB